

# HSP

### NOTES:

Current Rating: 2.0AMP  
 Withstand Voltage: 500V AC/DC  
 Contact Resistance: 20mΩ Max  
 Insulation Resistance: 1000MΩ Min  
 Operation Temperature: -40°C to +105°C

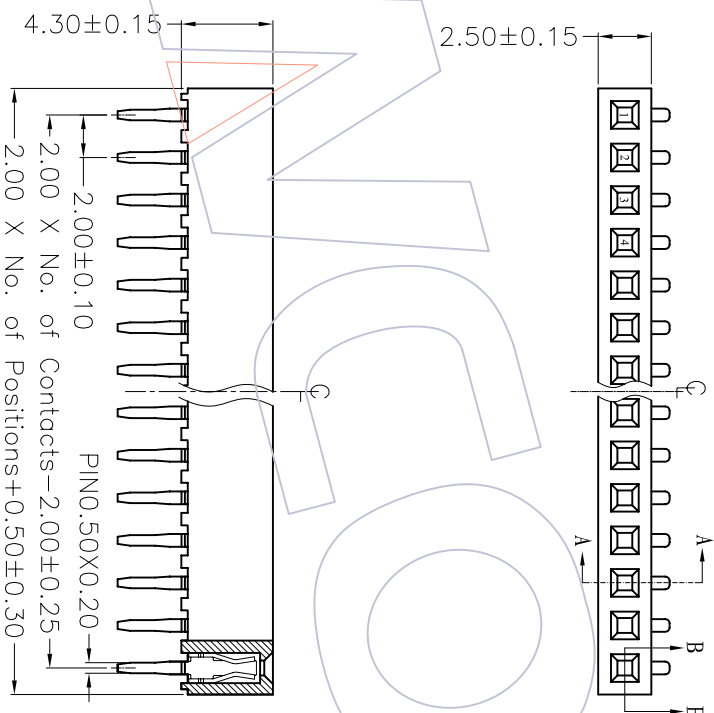
Contact Material: Phosphor Bronze  
 Contact plating: Au or Sn over Ni  
 Insulator Material: PA6T+30%G, F UL94V-0

## Ordering Information

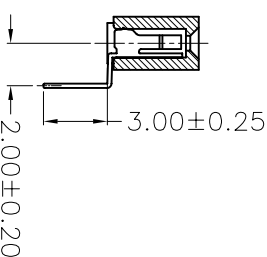
### 2243-1XX W XX CUNT 3

No. of Pins per ROW: 30-40PIN  
 Contact Plating: G=Gold Flash  
 GI=3μ"Gold  
 G3=5μ"Gold  
 G4=10μ"Gold  
 G5=15μ"Gold  
 G6=30μ"Gold  
 S0=Gold Flash/Tin  
 S1=3μ"Gold/Tin  
 S2=5μ"Gold/Tin  
 S3=10μ"Gold/Tin  
 S4=15μ"Gold/Tin  
 S5=30μ"Gold/Tin  
 SN=Tin

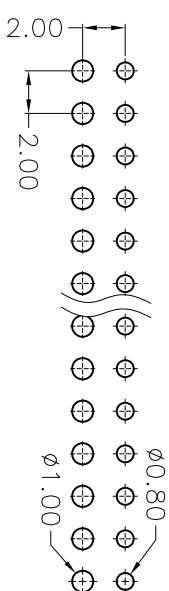
Packaging: T=Tube  
 P=Tube+CAP



SECTION B-B



SECTION A-A



Recommended P.C.B Layout(Top Side)  
 (PCB BOARD TOLERANCE±0.05)

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	OPERATION		DRAW	SCALE	UNIT	PART NO.	TITLE:
					Angle	± 3'					
A0	08/02/28	NEW			X.X	±0.40	Welling	3:1	mm	2243-1XXWXXCUNT3	菲2.00mm SINGLE Sentipede feet H=4.30
					X.XX	±0.25			A4		
					X.XXX	±0.15			1/1		
					Dim	TOL	APPROVE	PROJ.			

**WCON** 维峰五金电子有限公司  
 WAFER HARDWARE ELECTRONICS CO., LTD